

*B5*  
*contd*

further, the cards are not limited to IC cards, and the present invention can be applied for card-shaped products based on mount substrates with uneven surfaces.--.

**IN THE CLAIMS:**

Please amend claim 1 as follows. Pursuant to 37 C.F.R. § 1.121, the following is a clean copy of the amendments made to claim 1. A marked-up version of the amendments made to claim 1 is attached hereto.

*(D)*  
*(B)*  
*Sub C2 >*

~~1. (Once Amended) A process for producing IC cards, comprising the steps of: continuously feeding a mount substrate and simultaneously feeding a pair of sheet members on both surface sides of the mount substrate in such a manner that the mount substrate is interposed between the pair of sheet members; feeding an adhesive in fluid condition on the surface of the sheet members; and regulating a distance between the pair of sheet members into a constant spacing and hardening the adhesive by interposing the mount substrate between the surfaces of the sheet members on which the adhesive is fed.~~

Please add the following new claim 4:

*B*

--4. (New) The process of claim 1, wherein the distance between the sheet members is narrowed gradually.--

**REMARKS**

Claims 1-3 are pending in the application. Claim 1 has been amended. New claim 4, which depends from claim 1, has been added. Reexamination and allowance of the claims are requested.